| - | | | | _ | | | | | |
|-------|---------|-----|------|-------|------|------|------|------|---------|
| 1 | | 11 | | | | | | | |
| Da | - TAT | | | | | | | | |
| 15.05 | . NO | . 1 | | | | | | | 197 |
| | 7 | | | | | | | | |
| | , , , , | | | | | | | | i |

B.Tech DEGREE EXAMINATION, NOVEMBER 2023

Seventh Semester

18ECE205J - FPGA - BASED EMBEDDED SYSTEM DESIGN

(For the candidates admitted during the academic year 2020 - 2021 & 2021 - 2022)

Note:

i. Part - A should be answered in OMR sheet within first 40 minutes and OMR sheet should be handed over to hall invigilator at the end of 40th minute.

| Lim | e: 3 Hours | | Max. | Marks | : 100 |
|-----|---|---|--------|----------------|-------|
| | Mar | Marks BL | | | |
| | Answer all Qu | estions | | | |
| 1. | Which embedded design consider both the (A) Memory Design (C) Platform-based design | e hardware and software during its design?(B) Software/ hardware code sign(D) Peripheral design | 1 | 1 | 1 |
| 2. | A is one in which failure coul of a fire alarm system, or a pacemaker. (A) Soft Real-Time System | d produce a catastrophic result, e.g. failure (B) Firm Real-Time System | 1 | 1 | 1 |
| | (C) Hard Real-Time System | (D) Continuous System | | | |
| 3. | The maximum size of the External Data M (A) 84 Bytes (C) 80 Bytes | lemory space is bytes. (B) 64 Bytes (D) 81 Bytes | 1 | , and a second | 1 |
| 4. | are devices that convert one or analog signals for processing and control at (A) Sensor (C) FIFO | more physical parameters into digital or applications (B) Polling (D) Looping | 1 | 1 | 1 |
| _ | | (D) Looping | | | ^ |
| 5. | PSOC3 is a (A) True programmable embedded system-on-chip | (B) . Semi-programmable embedded system-on-chip | Manage | 1 | 2 |
| | (C) unprogrammable embedded system- on-chip | (D) programmable system-on-chip | | | |
| 6. | The signal sent to the device from the processor to the device after receiving an interrupt is | | | | 2 |
| | (A) Interrupt-acknowledge | (B) Return signal | | | |
| | (C) Service signal | (D) Permission signal | | | |
| 7. | An interrupt that can be temporarily ignore | ed is | 1 | 1 | 2 |
| | (A) Vectored interrupt | (B) Non-maskable interrupt | | | |
| | (C) Maskable interrupt | (D) High priority interrupt | | | |
| 8. | Which interrupt can make a change in the | 1 | 1 | 2 | |
| | (A) internal interrupt | (B) external interrupts | | | |
| | (C) exceptions | (D) software mode | | | |
|). | How many logic gates can be implemente logic devices (CPLDs)? | many logic gates can be implemented in the circuit by complex programmable devices (CPLDs)? | | 1 | 3 |
| | (A) . 10 | (B) 100 | | | |
| | (C) 1000 | (D) 10000 | | | |
| 10. | In JTAG programming, JTAG stands for | | 1 | 1 | 3 |
| | (A) Joint Texture Analysis Group | (B) Joint Technique Aided Group | | | |
| | (C) Joint Testing Array Group | (D) Joint Test Action Group | | | |

| 11. | programming is a combination of within a single chip providing a simple, severy cost-effective implementations | of non-volatility and re-programmability ecure, reliable and low-power solution for | News A | 1 | 3 | |
|-----|--|---|--------|-------|---|--|
| | (A) anti-fuse(C) EEPROM / Flash | (B) SRAM (D) DRAM | | | | |
| 12. | programmable devices in FPGA | an old technique of producing one-time | 1 | Press | 3 | |
| | (A) anti-fuse (C) EEPROM / Flash | (B) SRAM (D) DRAM | | | | |
| 13. | SESE point Stands for (A) Single End and Single Exit (C) Single Element Single Exit | 1 | and . | 4 | | |
| 14. | A is a high-level language produces executable for another platform | 1 | 1 | 4 | | |
| | (A) Cross – Development (C) Cross- assembler | (B) Cross – Compiler (D) Cross- Linker | | | | |
| 15. | A system program that combines separatel form suitable for execution is called | 1 | 1 | 4 | | |
| | (A) Assembler (C) Cross compiler | (B) Linking Loader (D) Debugger | | | | |
| 16. | The collection of run-time information on a | 1 | 1 | 5 | | |
| | (A) Processing (C) Partitioning | (B) Profiling (D) Planning | | | | |
| 17. | Iteration-level parallelism is also known as (A) Data level parallelism | (B) Bit level | 1 | 1 | 5 | |
| | (C) Instruction level | (D) Thread level | | | _ | |
| 18. | The go/done model is actually a (A) Multithreaded Model (C) Single thread model | (B) Network on-chip model (D) Co-processor Model | 1 | 1 | 5 | |
| 19. | Which mechanism can be used when the amount of time a feature runs is unknown? (A) Spin-lock (B) Coupling (C) Blocking (D) Rolling | | | | 5 | |
| 20. | The co-processor model is also known as (A) Multithreaded Model (C) Network on-chip model | (B) client/server model (D) Single thread model | i | 1 | 5 | |
| | PART - B (5 × 4 = 20 Marks) Answer any 5 Questions | | | | | |
| 21. | What is an embedded system? Explain its ex | 4 | 2 | 1 | | |
| 22. | List out the role of PLDs in embedded syste | 4 | 1 | I | | |
| 23. | Explain any three instructions of 8051 | 4 | 2 | 2 | | |
| 24. | List out the different addressing modes of 8 | 4 | 2 | 2 | | |
| 25. | Explain various slices used in Virtex 5 | 4 | 2 | 3 | | |
| 26. | Define the concept of Partitioning and Profi | 4 | 2 | 4 | | |
| 27. | Differentiate SIMD and MIMD architecture | 4 | 4 | 5 | | |

| | Mark | co | | |
|-----|--|----|---|---|
| 28. | (a) Explain in detail, the various embedded systems performance criteria with examples (OR) | 12 | 4 | 1 |
| | (b) Estimate the cause of interrupt latency in embedded systems and its problems. Also, explain the measures to reduce it. | | | |
| 29. | (a) Explain the functionality of PSoc3/5 architecture with 8051 implementations. | 12 | 2 | 2 |
| | (OR) | | | |
| | (b) Explain in detail about power management and clock distribution in PSoc3/5 architecture. | | | |
| 30. | (a) Explain the concept of configurable logic blocks, slices, and block RAM used in Xilinx Virtex 5 with a neat diagram. (OR) | 12 | 1 | 3 |
| | (b) Analyze and identify the various configuration blocks required for FPGA programming with a neat diagram | | | |
| 31. | (a) Discuss the platform FPGA components (FPGA-Field Programmable Gate Array). | 12 | 4 | 4 |
| | (OR) | | | |
| | (b) Explain the Platform FPGA Components. | | | |
| 32. | (a) Explain in detail the concept of on-chip and off-chip memory. (OR) | 12 | 2 | 5 |
| | (b) Explain the different levels of parallelism. | | | |
| | | | | |